EN: This Datasheet/Document is presented by the manufacturer.

Please visit our website for pricing and availability at www.hestore.hu.

TPS63802 2-A, High-efficient, Low I_Q Buck-boost Converter in DFN Package

1 Features

- Input voltage range: 1.3 V to 5.5 V
  - Device input voltage > 1.8 V for start-up
- Output voltage range: 1.8 V to 5.2 V (adjustable)
- 2-A output current for $V_I \geq 2.3$ V, $V_O = 3.3$ V
- High efficiency over the entire load range
  - 11-µA operating quiescent current
  - Power save mode and mode selection for forced PWM-mode
- Peak current buck-boost mode architecture
  - Defined transition points between buck, buck-boost, and boost operation modes
  - Forward and reverse current operation
  - Start-up into pre-biased outputs
- Safety and robust operation features
  - Integrated soft start
  - Overtemperature- and overvoltage-protection
  - True shutdown function with load disconnect
  - Forward and backward current limit
- Small solution size of 21.5 mm^2
  - Tiny SON/DFN package (similar to QFN)
  - Small 0.47-µH inductor
  - Works with a 22-µF minimum output capacitor
- Create a custom design using the TPS63802 with the WEBENCH® Power Designer

2 Applications

- System pre-regulator (tracking and telematics, portable POS, home automation, IP network camera)
- Point-of-load regulation (wired sensor, port/cable adapter and dongle, electronic smart lock, IoT)
- Battery back-up supply (electricity meter, data concentrator, power quality meter)
- Thermoelectric device supply (TEC, optical modules)
- General purpose voltage stabilizer and converter

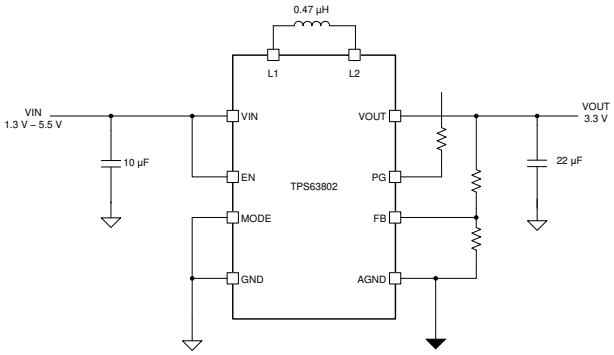
3 Description

The TPS63802 is a high efficiency, high output current buck-boost converter. Depending on the input voltage, it automatically operates in boost, buck, or in a novel 4-cycle buck-boost mode when the input voltage is approximately equal to the output voltage. The transitions between modes happen at defined thresholds and avoid unwanted toggling within the modes to reduce output voltage ripple. The device output voltages are individually set by a resistive divider within a wide output voltage range. An 11-µA quiescent current enables the highest efficiency for little to no-load conditions.

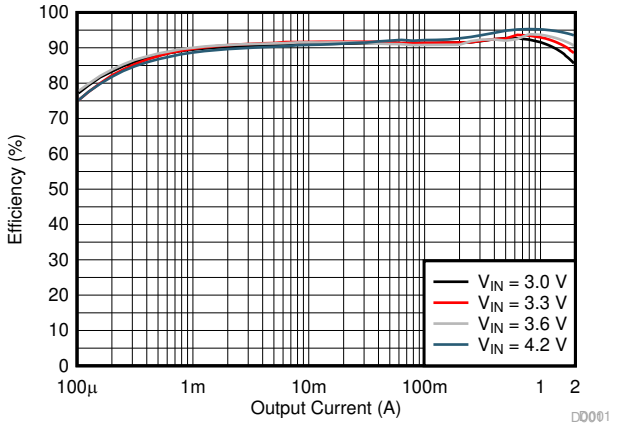
Device Information

PART NUMBER	PACKAGE(1)	BODY SIZE (NOM)
TPS63802	10-Pin VSON-HR (0.5 mm pitch)	3.0 mm × 2.0 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.



Typical Application



Efficiency vs Output Current (V_O = 3.3 V)

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

Table of Contents

1 Features....1
2 Applications....1
3 Description....1
4 Revision History....2
5 Description (continued)....3
6 Device Comparison Table....3
7 Pin Configuration and Functions....4
8 Specifications....5
8.1 Absolute Maximum Ratings....5
8.2 ESD Ratings....5
8.3 Recommended Operating Conditions....5
8.4 Thermal Information....5
8.5 Electrical Characteristics....6
8.6 Typical Characteristics....8
9 Detailed Description....9
9.1 Overview....9
9.2 Functional Block Diagram....9
9.3 Feature Description....10
9.4 Device Functional Modes....13
10 Application and Implementation....17
10.1 Application Information....17
10.2 Typical Application....17
11 Power Supply Recommendations....27
12 Layout....28
12.1 Layout Guidelines....28
12.2 Layout Example....28
13 Device and Documentation Support....29
13.1 Device Support....29
13.2 Documentation Support....29
13.3 Receiving Notification of Documentation Updates....29
13.4 Support Resources....30
13.5 Trademarks....30
13.6 Electrostatic Discharge Caution....30
13.7 Glossary....30
14 Mechanical, Packaging, and Orderable Information....30

4 Revision History

Changes from Revision C (June 2020) to Revision D (January 2021)	Page
• Updated the numbering format for tables, figures and cross-references throughout the document.	1

Changes from Revision B (September 2019) to Revision C (June 2020)	Page
• Added device comparison	3
• Changed 1x 22 µF to 2x 22 µF	19
• Changed Part Number from TPS63802RMW to TPS63802DLA	20
• Change MODE from High to Low in *Application Curves*	20
• Deleted layout guideline to separate AGND and PGND	28
• Changed Use a common-power GND, but connect AGND and PGND through via at a different layer. to Use a common ground node for power ground and a different one for control ground to minimize the effects of ground noise. Connect these ground nodes at any place close to one of the ground pins of the IC.	28

Changes from Revision A (January 2019) to Revision B (September 2019)	Page
• Changed the device status from *Advanced Information* to *Production Data*	1
• Changed package group name	1
• Added related documentation	29

Copyright © 2021 Texas Instruments Incorporated

5 Description (continued)

The TPS63802 comes in a 1.4 mm x 2.3 mm thermally enhanced HotRod™ dual flat no-lead (DFN) package. With the tiny bill-off material, the solution size can be small.

6 Device Comparison Table

PART NUMBER	OUTPUT VOLTAGE	$I_{(Q;VIN)}$ (TYP.)	$C_{(O,EFF)}$ (MIN.)	SWITCH CURRENT LIMIT BOOST (MIN.)	PACKAGE
TPS63802	Adjustable	11 µA	7 µF	4 A	VSON
SIMILAR TI PARTS					
TPS63805	Adjustable	11 µA	7 µF	4 A	WCSP
TPS63810 TPS63811	fixed: 3.3 V/3.45 V or I^2C programmable	15 µA	16 µF	5.2 A	WCSP

7 Pin Configuration and Functions

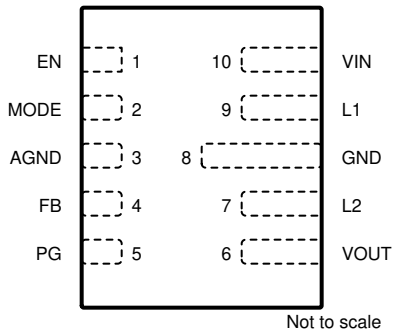


Figure 7-1. 10-Pin DLA Package (Top View)

Table 7-1. Pin Functions

PIN		DESCRIPTION
NAME	NO.	
EN	1	Device Enable input. Set HIGH to enable and LOW to disable. It must not be left floating.
MODE	2	PFM/PWM mode selection. Set LOW for power save mode, set HIGH for forced PWM mode. It must not be left floating.
AGND	3	Analog ground
FB	4	Voltage feedback sensing pin
PG	5	Power good indicator, open-drain output
VOUT	6	Power stage output
L2	7	Connection for inductor
GND	8	Power ground
L1	9	Connection for inductor
VIN	10	Supply voltage input

Copyright © 2021 Texas Instruments Incorporated

8 Specifications

8.1 Absolute Maximum Ratings

over junction temperature range (unless otherwise noted)(1)

		MIN	MAX	UNIT
Voltage(2)	VIN, L1, L2, EN, MODE, VOUT, FB, PG	–0.3	6	V
	L1, L2 (AC, less than 10 ns)	–3	9	V
Operating junction temperature, T_J		–40	150	°C
Storage temperature, T_{stg}		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values are with respect to network ground pin.

8.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

8.3 Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V_I	Input voltage		1.3 (1)		5.5	V
V_O	Output voltage		1.8		5.2 (2)	V
C_I	Effective capacitance connected to V_{IN}		4	5		µF
L	Effective inductance		0.37	0.47	0.57	µH
C_O	TPS63802 Effective capacitance connected to V_{OUT}	1.8 V ≤ V_O ≤ 2.3 V	10			µF
		V_O > 2.3 V	7	8.2		µF
T_J	Operating junction temperature	Operating junction temperature	–40		125	°C

(1) Minimum startup voltage of V_I > 1.8 V until power good
(2) V_O margin for accuracy and load steps is considerd in absolut maximum ratings

8.4 Thermal Information

over operating free-air temperature range (unless otherwise noted)(1)

THERMAL METRIC		TPS63802 VSON 10 PINS	UNIT
$R_{\Theta JA}$	Junction-to-ambient thermal resistance	81.0	°C/W
$R_{\Theta JC(top)}$	Junction-to-case (top) thermal resistance	36.4	°C/W
$R_{\Theta JB}$	Junction-to-board thermal resistance	23.4	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	0.9	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	23.5	°C/W
$R_{\Theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	n/a	°C/W

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

Copyright © 2021 Texas Instruments Incorporated

8.5 Electrical Characteristics

V_{IN}= 1.8 V to 5.5 V, V_{OUT} = 1.8 V to 5.2 V , T_J= –40°C to +125°C, typical values are at V_{IN}= 3.6 V, V_{OUT} = 3.3 V and T_J= 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
SUPPLY							
$V_{IN;LOAD}$	Minimum input voltage for full load, once started	I_{OUT} = 2 A, VOUT = 3.3 V, T_J = 25°C			2.3		V
$I_{Q;VIN}$	Quiescent current into VIN	TPS63802; T_J = 25°C, EN = V_{IN} = 3.6 V, V_{OUT} = 3.3 V, not switching			11		µA
I_{SD}	Shutdown current into VIN	EN = low, -40°C ≤ T_J ≤ 85°C, V_{IN} = 3.6 V, V_{OUT} = 0 V			45	600	nA
UVLO	Undervoltage lockout threshold	V_{IN} falling, VOUT ≥ 1.8 V, once started		1.2	1.25	1.29	V
	Undervoltage lockout threshold	V_{IN} rising		1.6	1.7	1.79	V
T_{SD}	Thermal shutdown	Temperature rising			150		°C
$T_{SD;HYST}$	Thermal shutdown hysteresis				20		°C
SOFT-START, POWER GOOD							
T_{ramp}	Soft-start, Current limit ramp time	T_J = 25°C, V_{IN} = 3.6 V, V_{OUT} = 3.3 V, I_O = 3.5 A, time from first switching to power good			224		µs
T_{delay}	Delay from EN-edge until rising V_{OUT}	T_J = 25°C, V_{IN} = 3.6 V, V_{OUT} = 3.3 V, Delay from EN-edge until rising first switching			321		µs
LOGIC SIGNALS EN, MODE							
$V_{THR;EN}$	Threshold Voltage rising for EN-Pin			1.07	1.1	1.13	V
$V_{THF;EN}$	Threshold Voltage falling for EN-Pin			0.97	1	1.03	V
V_{IH}	High-level input voltage			1.2			V
V_{IL}	Low-level input voltage					0.4	V
$V_{PG;rising}$	Power Good threshold voltage	VOUT rising, referenced to VOUT nominal			95		%
$V_{PG;falling}$		VOUT falling, referenced to VOUT nominal			90		%
$V_{PG;Low}$	Power Good low-level output voltage	I_{SINK} = 1 mA				0.4	V
$t_{PG;delay}$	Power Good delay time	V_{FB} falling			14		µs
I_{lkg}	Input leakage current				0.01	0.2	µA
OUTPUT							
I_{SD}	Shutdown current into VOUT	EN = low, -40°C ≤ T_J ≤ 85°C, V_{IN} = 3.6 V, V_{OUT} = 3.3 V			±0.5	±600	nA
V_{FB}	Feedback Regulation Voltage				500		mV
V_{FB}	Feedback Voltage accuracy	PWM mode		–1		1	%
	Overvoltage Protection Threshold	V_{OUT} rising		5.5	5.7	5.9	V
		V_{IN} rising		5.5	5.7	5.9	V
$I_{PWM/PFM}$	Peak Inductor Current to enter PFM-Mode	V_{IN} = 3.6 V; V_{OUT} = 3.3 V			1.06		A
I_{FB}	Feedback Input Bias Current	V_{FB} = 500 mV			5	100	nA
I_{PK}	Peak Current Limit, Boost Mode	TPS63802; V_{IN} ≥ 2.5 V		4	5	5.75	A
	Peak Current Limit, Buck-Boost Mode				5		A
	Peak Current Limit, Buck Mode				3.8		A
$I_{PK;Reverse}$	Peak Current Limit for Reverse Operation	V_I = 5 V, V_O = 3.3 V			–0.9		A
Buck $R_{DS;ON}$	High-side FET on-resistance	V_{IN} = 3 V, V_{OUT} = 3.3 V; $I_{(L2)}$ = 0.19 A	V_{IN} = 3 V, V_{OUT} = 3.3 V; I_O = 0.5 A		47		mΩ
	Low-side FET on-resistance	V_{IN} = 3 V, V_{OUT} = 3.3 V; $I_{(L2)}$ = 0.19 A	V_{IN} = 3 V, V_{OUT} = 3.3 V; I_O = 0.5 A		30		mΩ
Boost $R_{DS;ON}$	High-side FET on-resistance	V_{IN} = 3 V, V_{OUT} = 3.3 V; $I_{(L1)}$ = 0.19 A	V_{IN} = 3 V, V_{OUT} = 3.3 V; I_O = 0.5 A		43		mΩ
	Low-side FET on-resistance	V_{IN} = 3 V, V_{OUT} = 3.3 V; $I_{(L1)}$ = 0.19 A	V_{IN} = 3 V, V_{OUT} = 3.3 V; I_O = 0.5 A		18		mΩ

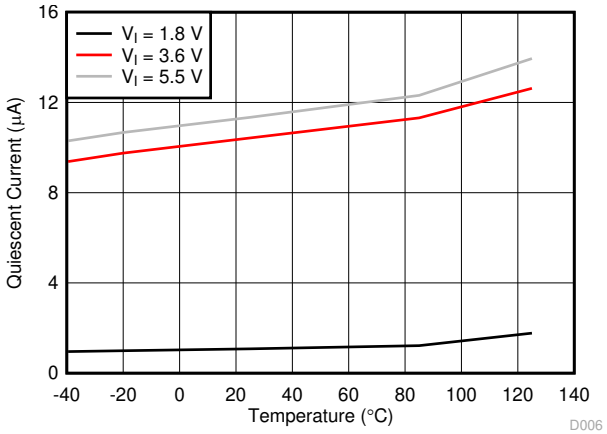
Copyright © 2021 Texas Instruments Incorporated

V_{IN}= 1.8 V to 5.5 V, V_{OUT} = 1.8 V to 5.2 V , T_J= –40°C to +125°C, typical values are at V_{IN}= 3.6 V, V_{OUT} = 3.3 V and T_J= 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{SW}	Inductor Switching Frequency, Boost Mode	V_{IN} = 2.3V, V_{OUT} = 3.3V, no Load, MODE = HIGH, T_J = 25°C		2.1		MHz
	Inductor Switching Frequency, Buck-Boost Mode	V_{IN} = 3.3V, V_{OUT} = 3.3V, no Load, MODE = HIGH, T_J = 25°C		1.4		MHz
	Inductor Switching Frequency, Buck Mode	V_{IN} = 4.3, V_{OUT} = 3.3V, no Load, MODE = HIGH, T_J = 25°C		1.6		MHz
	Line regulation	V_{IN} = 2.4 V to 5.5 V, V_{OUT} = 3.3V, I_{OUT} = 2 A		0.3		%
	Load regulation	V_{IN}= 3.6 V, V_{OUT} = 3.3V, I_{OUT} = 0 A to 2 A, forced-PWM mode		0.1		%

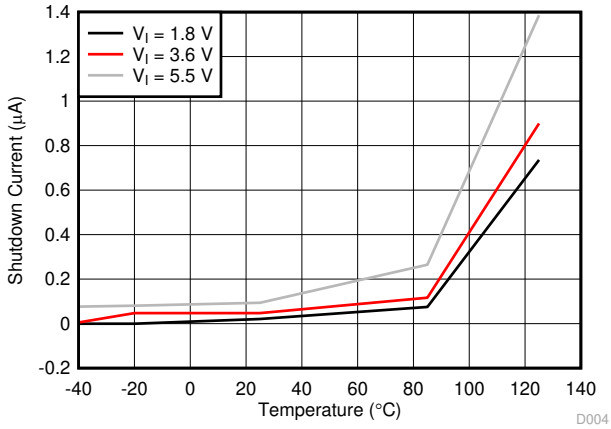
Copyright © 2021 Texas Instruments Incorporated

8.6 Typical Characteristics



MODE = LOW V_O = 3.3 V I_O = 0 mA, not switching

Figure 8-1. Quiescent Current vs. Temperature



EN = LOW

Figure 8-2. Shutdown Current vs. Temperature

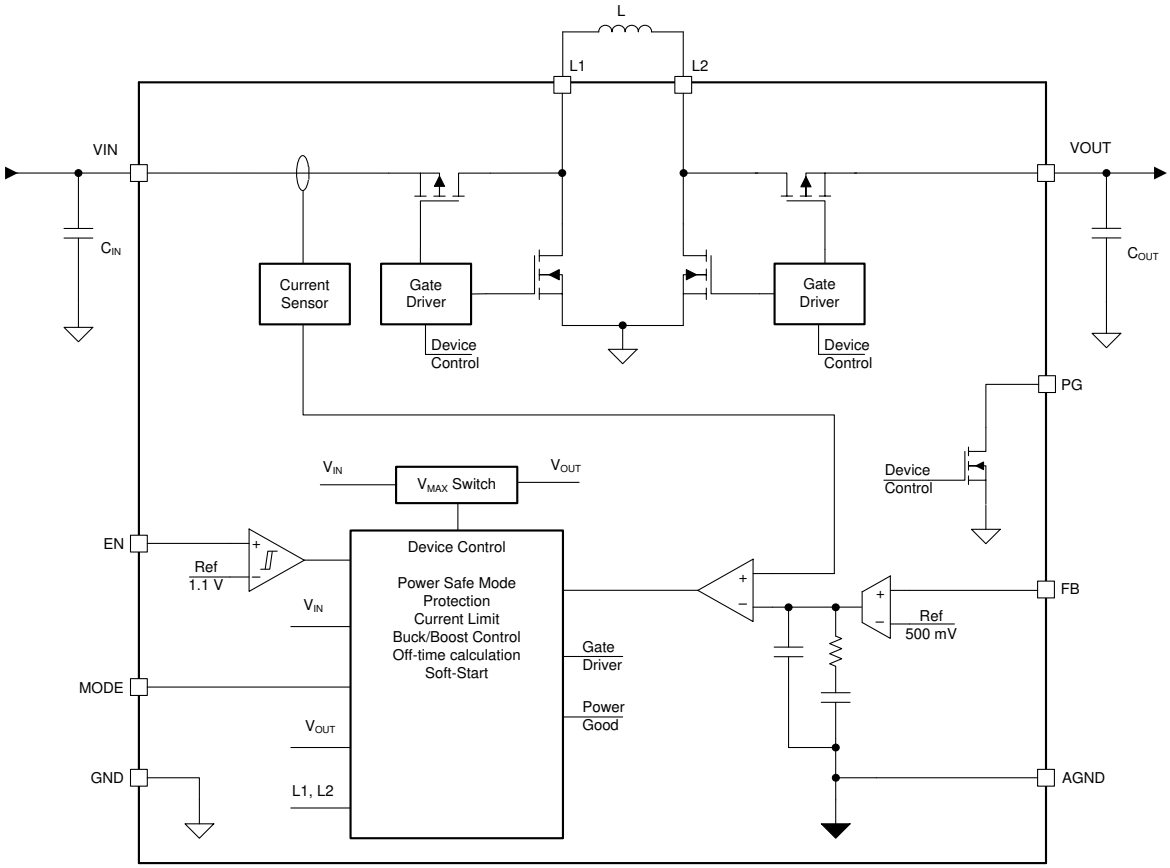
Copyright © 2021 Texas Instruments Incorporated

9 Detailed Description

9.1 Overview

The TPS63802 buck-boost converter uses four internal switches to maintain synchronous power conversion at all possible operating conditions. This enables the device to keep high efficiency over a wide input voltage and output load range. To regulate the output voltage at all possible input voltage conditions, the device automatically transitions between buck, buck-boost, and boost operation as required by the operating conditions. Therefore, it operates as a buck converter when the input voltage is higher than the output voltage, and as a boost converter when the input voltage is lower than the output voltage. When the input voltage is close to the output voltage, it operates in a 3-cycle buck-boost operation. In this mode, all four switches are active (see *Section 9.4.1.3*). The RMS current through the switches and the inductor is kept at a minimum to minimize switching and conduction losses. Controlling the switches this way allows the converter to always keep high efficiency over the complete input voltage range. The device provides a seamless transition between all modes.

9.2 Functional Block Diagram



9.3 Feature Description

9.3.1 Control Loop Description

The TPS63802 uses a peak current mode control architecture. It has an inner current loop where it measures the peak current of the boost high-side MOSFET and compares it to a reference current. This current is the output of the outer voltage loop. It measures the output voltage via the FB-pin and compares it with the internal voltage reference. That means, the outer voltage loop measures the voltage error (V_{REF}-V_{FB}), and transforms it into the system current demand (I_{REF}) for the inner current loop.

Figure 9-1 shows the simplified schematic of the control loop. The error amplifier and the type-2 compensation represent the voltage loop. The voltage output is converted into the reference current IREF and fed into the current comparator.

The scheme shows the skip-comparator handling the power-save mode (PFM) to achieve high efficiency at light loads. See *Section 9.4.2* for further details.

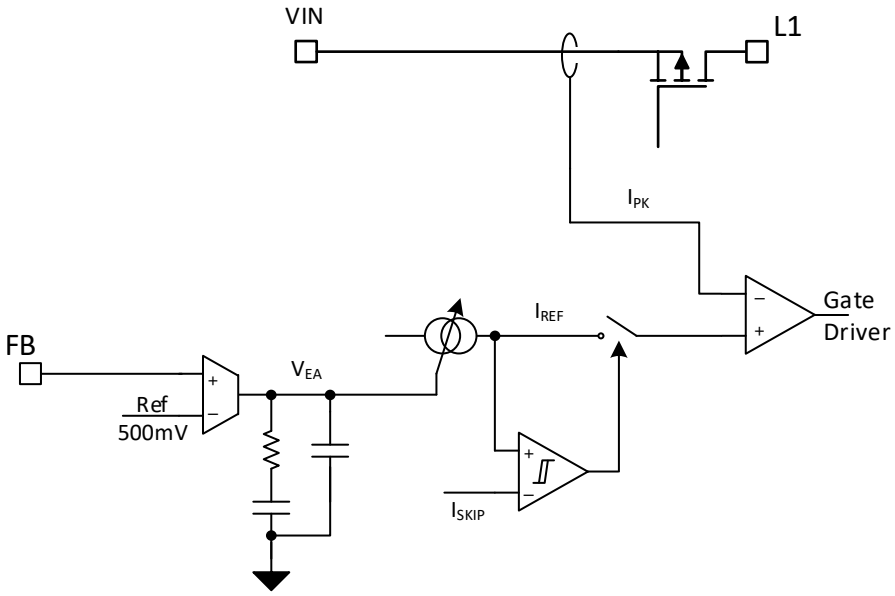


Figure 9-1. Control Loop Architecture Scheme

9.3.2 Precise Device Enable: Threshold- or Delayed Enable

The enable-pin is a digital input to enable or disable the device by applying a high or low level. The device enters shutdown when EN is set low. In addition, this input features a precise threshold and can be used as a comparator that enables and disables the part at a defined threshold. This allows you to drive the state by a slowly changing voltage and enables the use of an external RC network to achieve a precise power-up delay. The enable pin can also be used with an external voltage divider to set a user-defined minimum supply voltage. For proper operation, the EN pin must be terminated and must not be left floating.

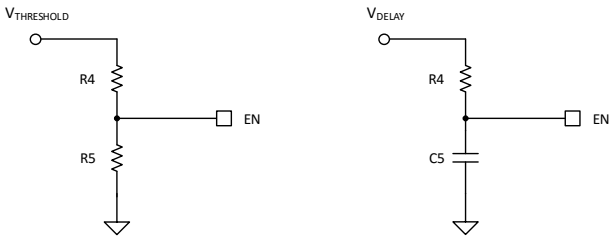


Figure 9-2. Circuit Example for How to Use the Precise Device Enable Feature

Copyright © 2021 Texas Instruments Incorporated

9.3.3 Mode Selection (PFM/PWM)

The mode-pin is a digital input to enable the automatic PWM/PFM mode that features the highest efficiency by allowing pulse-frequency-modulation for lower output currents. This mode is enabled by applying a low level. The device can be forced in PWM operation regardless of the output current to achieve minimum output ripple by applying a high level. This pin must not be left floating.

9.3.4 Undervoltage Lockout (UVLO)

To avoid mis-operation of the device at low input voltages, an undervoltage lockout is included. It activates the device once the input voltage (V_I) has increased the $UVLO_{rising}$ value. Once active, the device allows operation down to even smaller input voltages, which is determined by the $UVLO_{falling}$. This behavior requires V_O to be higher than the minimum value of 1.8 V.

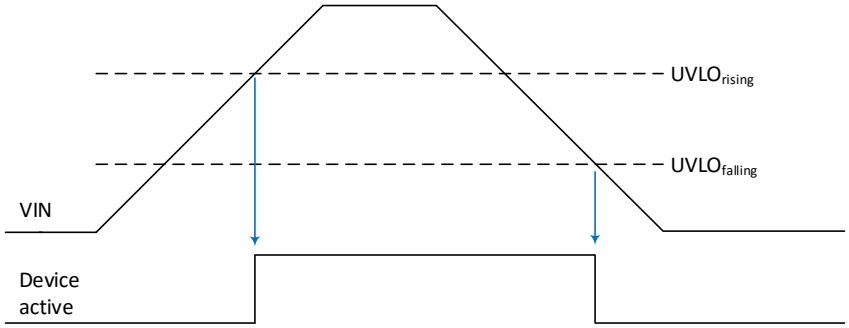


Figure 9-3. Rising and Falling Undervoltage Lockout Behavior

9.3.5 Soft Start

To minimize inrush current and output voltage overshoot during start-up, the device features a controlled soft start-up. After the device is enabled, the device starts all internal reference and control circuits within the enable delay time, T_{delay}. After that, the maximum switch current limit rises monotonically from 0 mA to the current limit. The loop stops switching once V_O is reached. This allows a quick output voltage ramp for small capacitors at the output. The bigger the output capacitor, the longer it takes to settle V_o. A potential load during start-up will lengthen the duration of the output voltage ramp as well. The gradual ramp of the current limit allows a small inrush current for no-load conditions, as well as the possibility to start into high loads at start-up.

The converter can start-up into pre-biased loads by a forced operation in PFM during the soft-start until the first switching cycle request from the output voltage control loop.

Copyright © 2021 Texas Instruments Incorporated

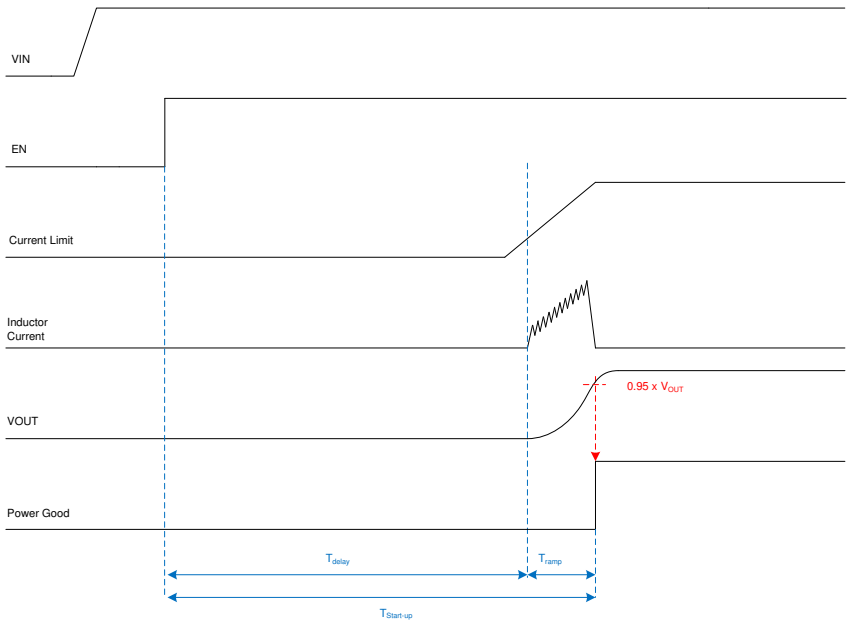


Figure 9-4. Device Start-up Scheme

9.3.6 Adjustable Output Voltage

The device's output voltage is adjusted by applying an external resistive divider between V_O, the FB-pin, and GND. This allows you to program the output voltage in the recommended range. The divider must provide a low-side resistor of less than 100 kΩ. The high-side resistor is chosen accordingly.

9.3.7 Overtemperature Protection - Thermal Shutdown

The device has a built-in temperature sensor which monitors the junction temperature. If the temperature exceeds the threshold, the device stops operating. As soon as the IC temperature has decreased below the programmed threshold, it starts operating again. There is a built-in hysteresis to avoid unstable operation at junction temperatures at the overtemperature threshold.

9.3.8 Input Overvoltage - Reverse-Boost Protection (IVP)

The TPS63802 can operate in reverse mode where the device transfers energy from the output back to the input. If the source is not able to sink the revers current, the negative current builds up a charge to the input capacitance and V_{IN} rises. To protect the device and other components from that scenario, the device features an input voltage protection (IVP) for reverse boost operation. Once the input voltage is above the threshold, the converter forces PFM mode and the negative current operation is interrupted.

The PG signal goes low to indicate that behavior.

9.3.9 Output Overvoltage Protection (OVP)

In case of a broken feedback-path connection, the device can loose V_O information and is not able to regulate. To avoid an uncontrolled boosting of V_O, the TPS63802 features output overvoltage protection. It measures the voltage on the VOUT pin and stops switching when V_O is greater than the threshold to avoid harm to the converter and other components.

9.3.10 Power-Good Indicator

The power good goes high-impedance once the output is above 95% of the nominal voltage, and is driven low once the output voltage falls below typically 90% of the nominal voltage. This feature also indicates overvoltage and device shutdown cases as shown in Table 9-1. The PG pin is an open-drain output and is specified to sink up to 1 mA. The power-good output requires a pullup resistor connecting to any voltage rail less than 5.5 V. The PG signal can be used to sequence multiple rails by connecting it to the EN pin of other converters. Leave the PG pin unconnected when not used.

Copyright © 2021 Texas Instruments Incorporated

Table 9-1. Power-Good Indicator Truth Table

LOGIC SIGNALS					PG LOGIC STATUS
EN	V_O	V_I	OVP	IVP	
X	< 1.8 V	< UVLO_R	X	X	Undefined
LOW	X	> UVLO_F	X	X	LOW
HIGH	V_O < 0.9 × target-V_O	> 1.3V	X	X	LOW
HIGH	X	> UVLO_F	HIGH	X	LOW
HIGH	X	> UVLO_F	X	HIGH	LOW
HIGH	V_O > 0.95 × target-V_O	> UVLO_F	LOW	LOW	HIGH Z

9.4 Device Functional Modes

9.4.1 Peak-Current Mode Architecture

The TPS63802 is based on a peak-current mode architecture. The error amplifier provides a peak-current target (voltage that is translated into an equivalent current, see Figure 9-1), based on the current demand from the voltage loop. This target is compared to the actual inductor current during the ON-time. The ON-time is ended once the inductor current is equal to the current target and OFF-time is initiated. The OFF-time is calculated by the control and a function of V_I and V_O.

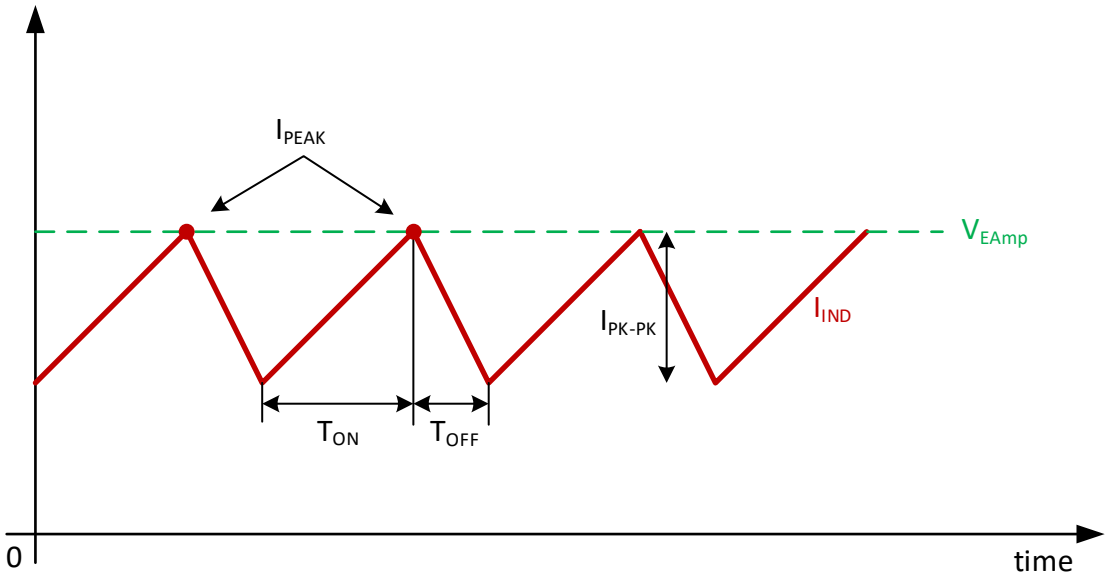


Figure 9-5. Peak-Current Architecture Operation

9.4.1.1 Reverse Current Operation, Negative Current

When the TPS63802 is forced to PWM operation (MODE = HIGH), the device current can flow in reverse direction. This happens by the negative current capability of the TPS63802 . The error amplifier provides a peak-current target (voltage that is translated into an equivalent current, see Figure 9-1), even if the target has a negative value. The maximum average current is even more negative than the peak current.

Copyright © 2021 Texas Instruments Incorporated

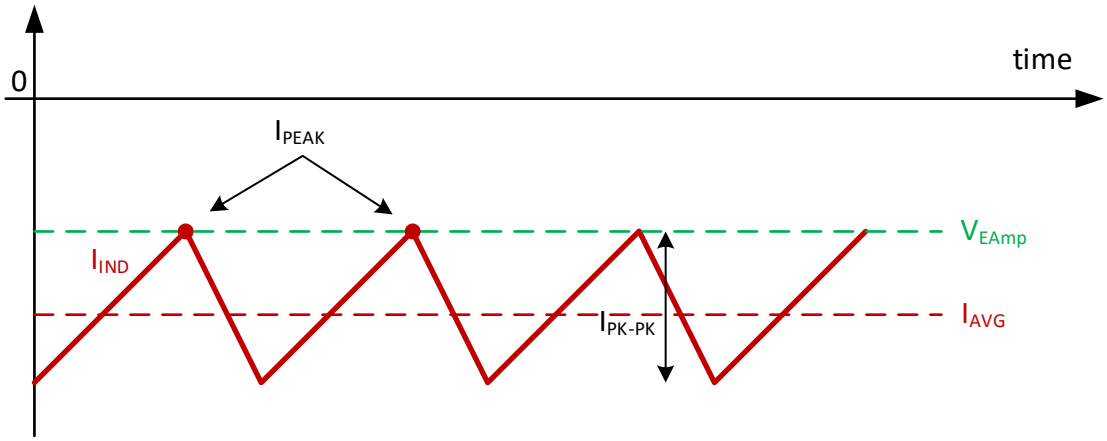


Figure 9-6. Peak-Current Operation, Reverse Current

9.4.1.2 Boost Operation

When V_I is smaller than V_O (and the voltages are not close enough to trigger buck-boost operation), the TPS63802 operates in boost mode where the boost high-side and low-side switches are active. The buck high-side switch is always turned on and the buck low-side switch is always turned off. This lets the TPS63802 operate as a classical boost converter.

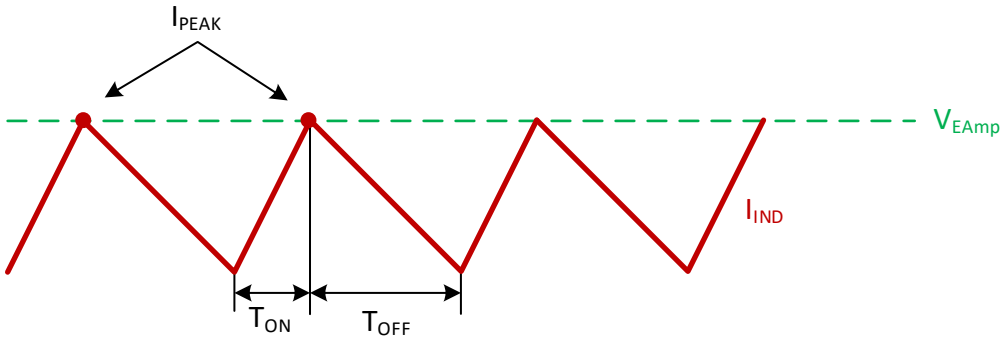


Figure 9-7. Peak-Current Boost Operation

9.4.1.3 Buck-Boost Operation

When V_I is close to V_O, the TPS63802 operates in buck-boost mode where all switches are active and the device repeats 3-cycles:

- T_{ON}: Boost-charge phase where boost low-side and buck high-side are closed and the inductor current is built up
- T_{OFF}: Buck discharge phase where boost high-side and buck low-side are closed and the inductor is discharged
- T_{COM}: V_I connected to V_O where all high-side switches are closed and the input is connected to the output

Copyright © 2021 Texas Instruments Incorporated

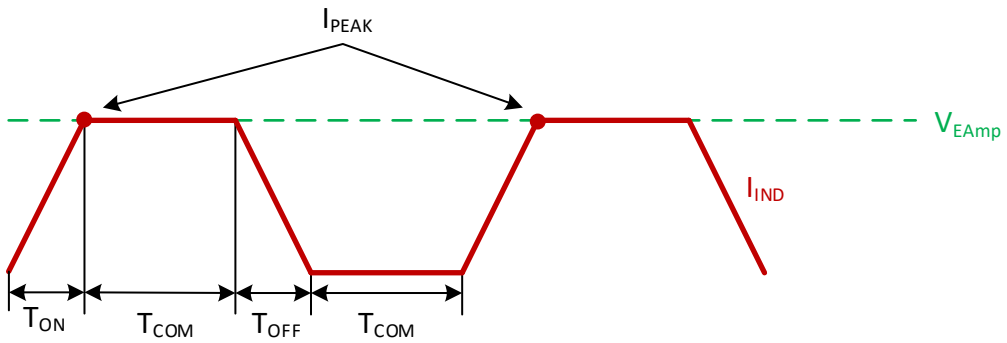


Figure 9-8. Peak-Current Buck-Boost Operation

9.4.1.4 Buck Operation

When V_I is greater than V_O (and the voltages are not close enough to trigger buck-boost operation), the TPS63802 operates in buck mode where the buck high-side and low-side switches are active. The boost high-side switch is always turned on and the boost low-side switch is always turned off. This lets the TPS63802 operate as a classical buck converter.

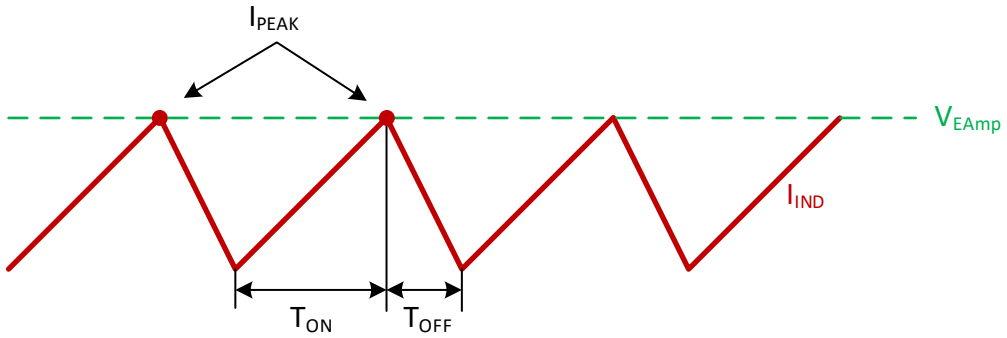


Figure 9-9. Peak-Current Buck Operation

9.4.2 Power Save Mode Operation

Besides continuos conduction mode (PWM), the TPS63802 features power safe mode (PFM) operation to achieve high efficiency at light load currents. This is implemented by pausing the switching operation, depending on the load current.

The skip comparator manages the switching or pause operation. It compares the current demand signal from the voltage loop, I_{REF}, with the skip threshold, I_{SKIP}, as shown in Figure 9-1. If the current demand is lower than the skip value, the comparator pauses switching operation. If the current demand goes higher (due to falling V_O), the comparator activates the current loop and allows switching according to the loop behavior. Whenever the current loop has risen V_O by bringing charge to the output, the voltage loop output, I_{REF} (respectively V_{EA}), decreases. When I_{REF} falls below I_{SKIP}-hysteresis, it automatically pauses again.

Copyright © 2021 Texas Instruments Incorporated

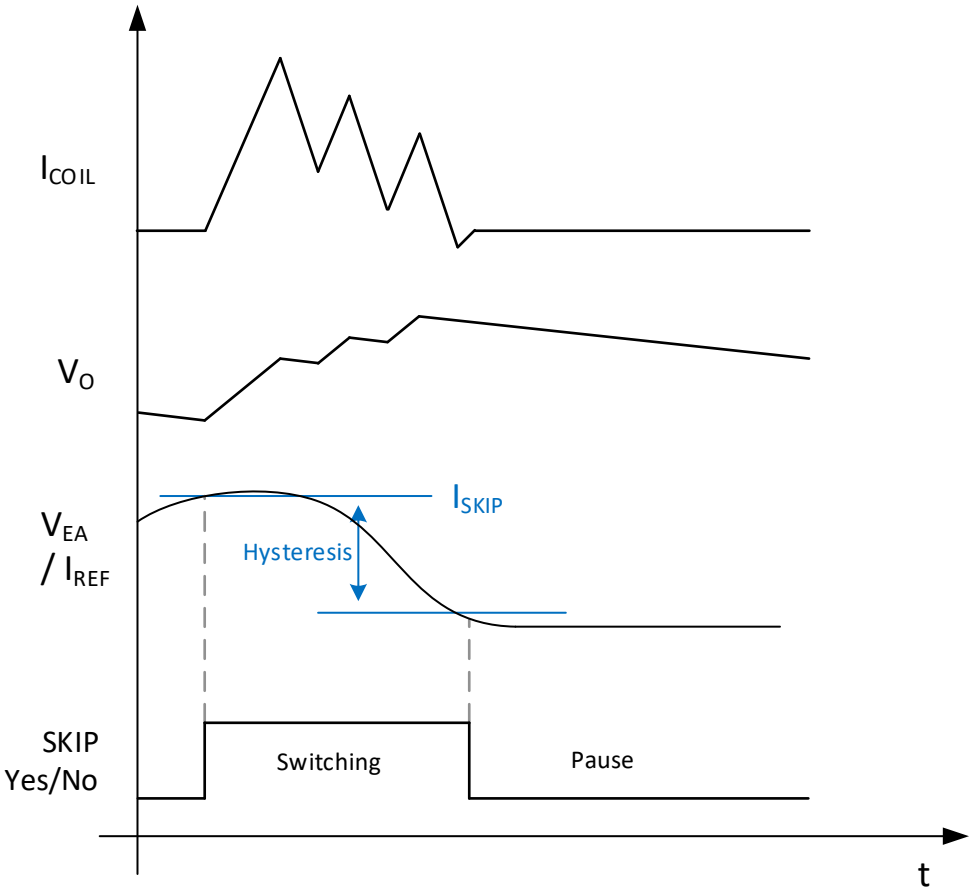


Figure 9-10. Power Safe Mode Operation Curves

9.4.2.1 Current Limit Operation

To limit current and protect the device and application, the maximum peak inductor current is limited internally on the IC. It is measured at the buck high-side switch which turns into an input current detection. To provide a certain load current across all operation modes, the boost and buck-boost peak current limit is higher than in buck mode. It limits the input current and allows no further increase of the delivered current. When using the device in this mode, it behaves similar to a current source.

The current limit depends on the operation mode (buck, buck-boost, or boost mode).

Copyright © 2021 Texas Instruments Incorporated

10 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

10.1 Application Information

The TPS63802 is a high efficiency, low quiescent current, non-inverting buck-boost converter, suitable for applications that need a regulated output voltage from an input supply that can be higher or lower than the output voltage.

10.2 Typical Application

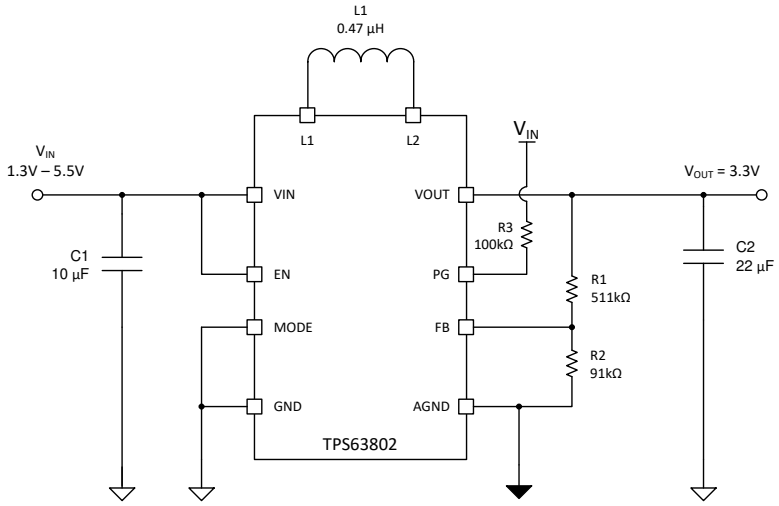


Figure 10-1. 3.3 V_{OUT} Typical Application

10.2.1 Design Requirements

The design guideline provides a component selection to operate the device within *Table 10-1*.

Table 10-1 shows the list of components for the application characteristic curves.

Table 10-1. Matrix of Output Capacitor and Inductor Combinations

NOMINAL INDUCTOR VALUE [µH](1)	NOMINAL OUTPUT CAPACITOR VALUE [µF](2)				
	10	22	47	66	100
0.47	-	+ (3)	+	+	+

(1) Inductor tolerance and current derating is anticipated. The effective inductance can vary by 20% and –30%.
(2) Capacitance tolerance and DC bias voltage derating is anticipated. The effective capacitance can vary by 20% and –50%.
(3) TPS63802 typical application. Other check marks indicate possible filter combinations.

10.2.2 Detailed Design Procedure

The first step is the selection of the output filter components. To simplify this process, *Section 8.1* outlines minimum and maximum values for inductance and capacitance. Take tolerance and derating into account when selecting nominal inductance and capacitance.

10.2.2.1 Custom Design With WEBENCH® Tools

Click here to create a custom design using the TPS63802 device with the WEBENCH® Power Designer.

Copyright © 2021 Texas Instruments Incorporated

1. Start by entering the input voltage (V_{IN}), output voltage (V_{OUT}), and output current (I_{OUT}) requirements.
2. Optimize the design for key parameters such as efficiency, footprint, and cost using the optimizer dial.
3. Compare the generated design with other possible solutions from Texas Instruments.

The WEBENCH Power Designer provides a customized schematic along with a list of materials with real-time pricing and component availability.

In most cases, these actions are available:

- Run electrical simulations to see important waveforms and circuit performance
- Run thermal simulations to understand board thermal performance
- Export customized schematic and layout into popular CAD formats
- Print PDF reports for the design, and share the design with colleagues

Get more information about WEBENCH tools at www.ti.com/WEBENCH.

10.2.2.2 Inductor Selection

The inductor selection is affected by several parameters such as the following:

- Inductor ripple current
- Output voltage ripple
- Transition point into power save mode
- Efficiency

See Table 10-2 for typical inductors.

For high efficiencies, the inductor must have a low DC resistance to minimize conduction losses. Especially at high-switching frequencies, the core material has a high impact on efficiency. When using small chip inductors, the efficiency is reduced, mainly due to higher inductor core losses. This needs to be considered when selecting the appropriate inductor. The inductor value determines the inductor ripple current. The larger the inductor value, the smaller the inductor ripple current and the lower the conduction losses of the converter. Conversely, larger inductor values cause a slower load transient response. To avoid saturation of the inductor, the peak current for the inductor in steady-state operation is calculated using Equation 2. Only the equation which defines the switch current in boost mode is shown because this provides the highest value of current and represents the critical current value for selecting the right inductor.

$$\text{Duty Cycle Boost} \qquad D = \frac{V_{OUT} - V_{IN}}{V_{OUT}} \tag{1}$$

$$I_{PEAK} = \frac{Iout}{\eta \times (1 - D)} + \frac{Vin \times D}{2 \times f \times L} \tag{2}$$

where

- D = Duty Cycle in Boost mode
- *f* = Converter switching frequency
- L = Inductor value
- η = Estimated converter efficiency (use the number from the efficiency curves or 0.9 as an assumption)

Note

The calculation must be done for the minimum input voltage in boost mode.

Calculating the maximum inductor current using the actual operating conditions gives the minimum saturation current of the inductor needed. It is recommended to choose an inductor with a saturation current 20% higher than the value calculated using Equation 2. Table 10-2 lists the possible inductors.

Copyright © 2021 Texas Instruments Incorporated

Table 10-2. List of Recommended Inductors

INDUCTOR VALUE [µH]	SATURATION CURRENT [A]	DCR [mΩ]	PART NUMBER	MANUFACTURER(1)	SIZE (LxWxH mm)
0.47	5.4	7.6	XFL4015-471ME	Coilcraft	4 x 4 x 2
0.47	5.5	26	DFE201612E	Toko	2.0 x 1.6 x 1.2

(1) See *Third-party Products Disclaimer*.

10.2.2.3 Output Capacitor Selection

For the output capacitor, it is recommended to use small ceramic capacitors placed as close as possible to the VOUT and PGND pins of the IC. The recommended nominal output capacitor value is a single 22 µF for all programmed output voltages ≤ 3.6 V. Above that voltage, 2x 22 µF capacitors are recommended.

It is important that the effective capacitance is given according to the recommended value in *Section 8.3*. In general, consider DC bias effects resulting in less effective capacitance. The choice of the output capacitance is mainly a trade-off between size and transient behavior since higher capacitance reduces transient response overshoot and undershoot and increases transient response time. Table 10-3 lists possible output capacitors.

There is no upper limit for the output capacitance value.

Table 10-3. List of Recommended Capacitors (1)

CAPACITOR [µF]	VOLTAGE RATING [V]	ESR [mΩ]	PART NUMBER	MANUFACTURER	SIZE (METRIC)
22	6.3	10	GRM188R60J226MEA0	Murata	0603 (1608)
22	6.3	10	GRM187R61A226ME15	Murata	0603 (1608)
22	10	40	GRM188R61A226ME15	Murata	0603 (1608)
22	10	10	GRM187R60J226ME15	Murata	0603 (1608)
47	6.3	43	GRM188R60J476ME15	Murata	0603 (1608)
47	6.3	43	GRM219R60J476ME44	Murata	0805 (2012)

(1) See *Third-party Products Disclaimer*.

10.2.2.4 Input Capacitor Selection

A 10 µF input capacitor is recommended to improve line transient behavior of the regulator and EMI behavior of the total power supply circuit. An X5R or X7R ceramic capacitor placed as close as possible to the VIN and PGND pins of the IC is recommended. This capacitance can be increased without limit. If the input supply is located more than a few inches from the TPS63802 converter, additional bulk capacitance can be required in addition to the ceramic bypass capacitors. An electrolytic or tantalum capacitor with a value of 47 µF is a typical choice.

Table 10-4. List of Recommended Capacitors (1)

CAPACITOR [µF]	VOLTAGE RATING [V]	ESR [mΩ]	PART NUMBER	MANUFACTURER	SIZE (METRIC)
10	6.3	10	GRM188R60J106ME84	Murata	0603 (1608)
10	10	40	GRM188R61A106ME69	Murata	0603 (1608)
22	6.3	10	GRM188R60J226MEA0	Murata	0603 (1608)

10.2.2.5 Setting The Output Voltage

The output voltage is set by an external resistor divider. The resistor divider must be connected between VOUT, FB, and GND. The feedback voltage is 500 mV nominal. The low-side resistor R2 (between FB and GND) must not exceed 100 kΩ. The high-side resistor (between FB and VOUT) R1 is calculated by Equation 3.

$$R1 = R2 \times \left(\frac{V_{OUT}}{V_{FB}} - 1 \right) \quad (3)$$

Copyright © 2021 Texas Instruments Incorporated

where

- V_{FB} = 500 mV

Table 10-5. Resistor Selection for Typ. Voltages

V_O [V]	R1 [kΩ]	R2 [kΩ]
2.5	365	91
3.3	511	91
3.6	562	91
5	806	91

10.2.3 Application Curves

Table 10-6. Components for Application Characteristic Curves (1)

REFERENCE	DESCRIPTION	PART NUMBER	MANUFACTURER	COMMENT
	TPS63802 2 A Buck-Boost Converter (2 mm x 3 mm QFN)	TPS63802DLA	Texas Instruments	
L1	0.47 µH, 4 mm x 4 mm x 1.5 mm, 5.4 A, 7.6 mΩ	XFL4015-471ME	Coilcraft	
C1	10 µF, 0603, Ceramic Capacitor, ±20%, 6.3 V	GRM188R60J106ME84	Murata	
C2	1x 22 µF, 0603, Ceramic Capacitor, ±20%, 6.3 V	GRM188R60J226MEA0	Murata	$V_O \leq 3.6$ V
C2	2x 22 µF, 0603, Ceramic Capacitor, ±20%, 6.3 V	GRM188R60J226MEA0	Murata	$V_O > 3.6$ V
R1	511 kΩ, 0603 Resistor, 1%, 100 mW	Standard	Standard	V_O = 3.3 V
R1	562 kΩ, 0603 Resistor, 1%, 100 mW	Standard	Standard	V_O = 3.6 V
R1	806 kΩ, 0603 Resistor, 1%, 100 mW	Standard	Standard	V_O = 5 V
R2	91 kΩ, 0603 Resistor, 1%, 100 mW	Standard	Standard	
R3	100 kΩ, 0603 Resistor, 1%, 100 mW	Standard	Standard	

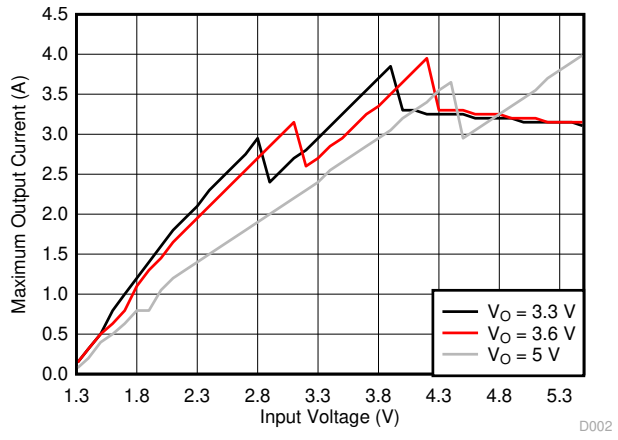
(1) See *Third-party Products Disclaimer*.

Copyright © 2021 Texas Instruments Incorporated

Table 10-7. Typical Characteristics Curves

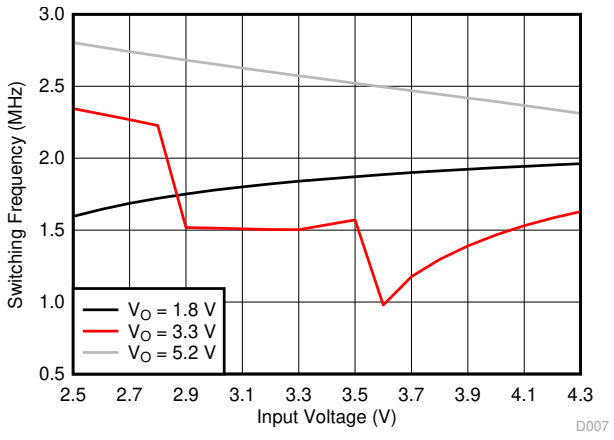
PARAMETER	CONDITIONS	FIGURE
Output Current Capability		
Typical Output Current Capability versus Input Voltage	V_O = 3.3 V	Figure 10-2
Switching Frequency		
Typical Inductor Switching Frequency versus Input Voltage	I_O = 0 A, MODE = High	Figure 10-3
Typical Inductor Burst Frequency versus Output Current	V_O = 3.3 V	Figure 10-4
Efficiency		
Efficiency versus Output Current (PFM/PWM)	V_I = 2.5 V to 4.2 V, V_O = 3.3 V, MODE = Low	Figure 10-5
Efficiency versus Output Current (PWM only)	V_I = 2.5 V to 4.2 V, V_O = 3.3 V, MODE = High	Figure 10-6
Efficiency versus Output Current (PFM/PWM)	V_I = 1.8 V to 5 V, V_O = 3.3 V, MODE = Low	Figure 10-7
Efficiency versus Output Current (PWM only)	V_I = 1.8 V to 5 V, V_O = 3.3 V, MODE = High	Figure 10-8
Efficiency versus. Input Voltage (PFM/PWM)	V_O = 3.3 V, MODE = Low	Figure 10-9
Efficiency versus Input Voltage (PWM only)	I_O = 1 A, MODE = High	Figure 10-10
Regulation Accuracy		
Load Regulation, PWM Operation	V_O = 3.3 V, MODE = High	Figure 10-11
Load Regulation, PFM/PWM Operation	V_O = 3.3 V, MODE = Low	Figure 10-12
Line Regulation, PWM Operation	I_O = 1 A, MODE = High	Figure 10-13
Line Regulation, PFM/PWM Operation	I_O = 1 A, MODE = Low	Figure 10-14
Switching Waveforms		
Switching Waveforms, PFM Boost Operation	V_I = 2.3 V, V_O = 3.3 V, MODE = Low	Figure 10-15
Switching Waveforms, PFM Buck-Boost Operation	V_I = 3.3 V, V_O = 3.3 V, MODE = Low	Figure 10-16
Switching Waveforms, PFM Buck Operation	V_I = 4.3 V, V_O = 3.3 V, MODE = Low	Figure 10-17
Switching Waveforms, PWM Boost Operation	V_I = 2.3 V, V_O = 3.3 V, MODE = High	Figure 10-18
Switching Waveforms, PWM Buck-Boost Operation	V_I = 3.3 V, V_O = 3.3 V, MODE = High	Figure 10-19
Switching Waveforms, PWM Buck Operation	V_I = 4.3 V, V_O = 3.3 V, MODE = High	Figure 10-20
Transient Performance		
Load Transient, PFM/PWM Boost Operation	V_I = 2.5 V, V_O = 3.3 V, Load = 100 mA to 1A, MODE = Low	Figure 10-21
Load Transient, PFM/PWM Buck-Boost Operation	V_I = 3.3 V, V_O = 3.3 V, Load = 100 mA to 1A, MODE = Low	Figure 10-22
Load Transient, PFM/PWM Buck Operation	V_I = 4.2 V, V_O = 3.3V, Load = 100 mA to 1A, MODE = Low	Figure 10-23
Load Transient, PWM Boost Operation	V_I = 2.5 V, V_O = 3.3 V, Load = 100 mA to 1A, MODE = High	Figure 10-24
Load Transient, PWM Buck-Boost Operation	V_I = 3.3 V, V_O = 3.3 V, Load = 100 mA to 1A, MODE = High	Figure 10-25
Load Transient, PWM Buck Operation	V_I = 4.2 V, V_O = 3.3 V, Load = 100 mA to 1A, MODE = High	Figure 10-26
Line Transient, PWM Operation	V_I = 2.3 V to 4.3 V, V_O = 3.3 V, Load = 0.5 A , MODE = Low	Figure 10-27
Line Transient, PWM Operation	V_I = 2.3 V to 4.3 V, V_O = 3.3 V, Load = 1 A , MODE = Low	Figure 10-28
Line Transient, PWM Operation	V_I = 3 V to 3.6 V, V_O = 3.3 V, Load = 0.5 A , MODE = Low	Figure 10-29
Start-up		
Start-up Behavior from Rising Enable, PFM Operation	V_I = 2.2 V, V_O = 3.3 V, Load = 10 mA, MODE = Low	Figure 10-30
Start-up Behavior from Rising Enable, PWM Operation	V_I = 2.2 V, V_O = 3.3 V, Load = 10 mA, MODE = High	Figure 10-31

Copyright © 2021 Texas Instruments Incorporated



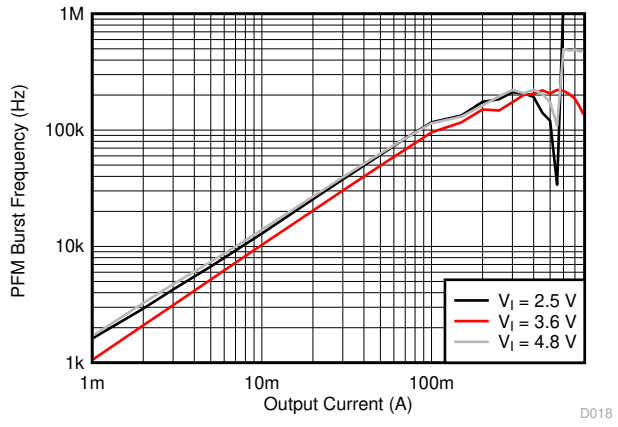
MODE = High

Figure 10-2. Typical Output Current Capability versus Input Voltage



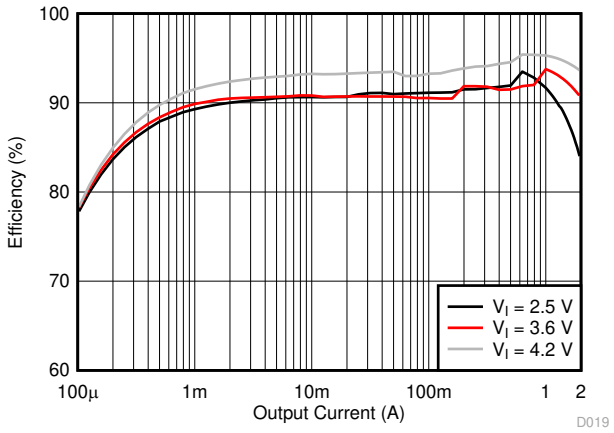
I_O = 0 A MODE = High V_I rising

Figure 10-3. Typical Inductor Switching Frequency versus Input Voltage



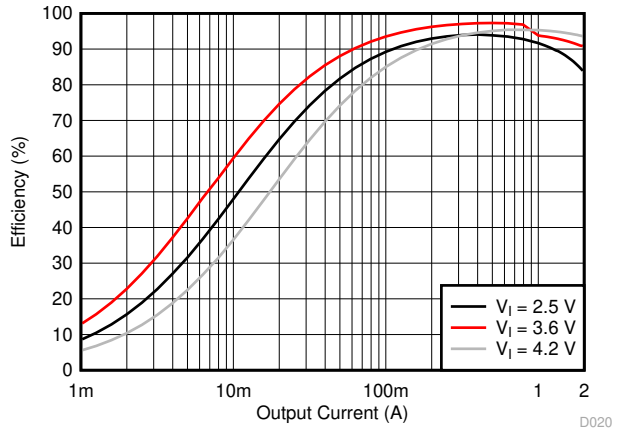
V_O = 3.6 V MODE = Low

Figure 10-4. Typical Inductor Burst Frequency versus Output Current



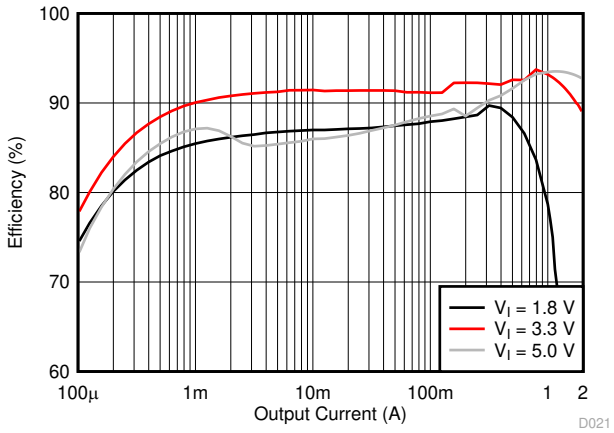
V_O = 3.3 V MODE = Low

Figure 10-5. Efficiency versus Output Current (PFM/PWM)



V_O = 3.3 V MODE = High

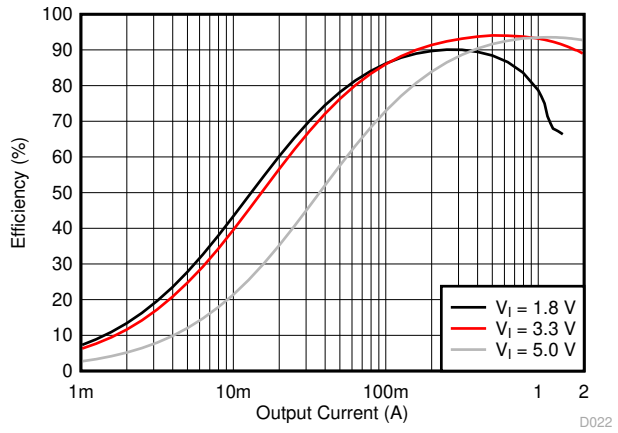
Figure 10-6. Efficiency versus Output Current (PWM Only)



V_O = 3.3 V MODE = Low

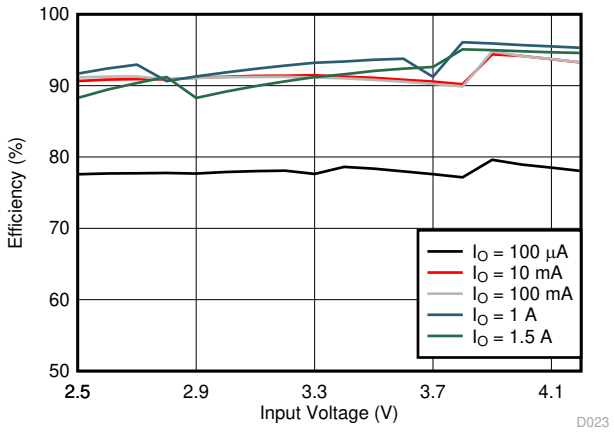
Figure 10-7. Efficiency versus Output Current (PFM/PWM)

Copyright © 2021 Texas Instruments Incorporated



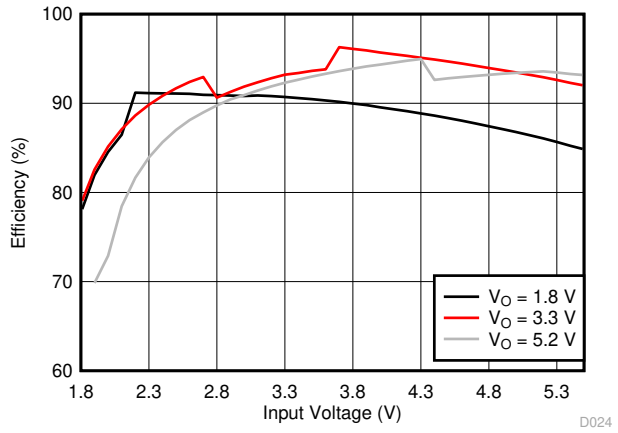
V_O = 3.3 V MODE = High

Figure 10-8. Efficiency versus Input Voltage (PWM Only)



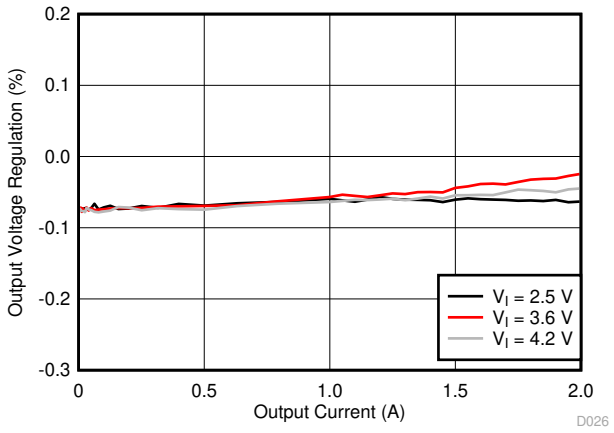
V_O = 3.3 V MODE = Low

Figure 10-9. Efficiency versus Input Voltage (PFM/PWM)



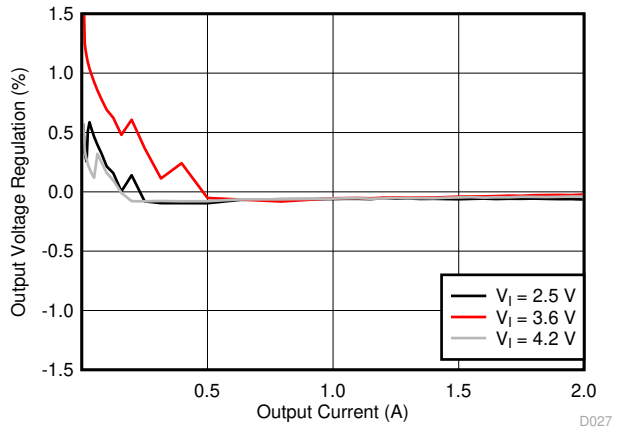
I_O = 1 A MODE = Low

Figure 10-10. Efficiency versus Input Voltage (PWM Only)



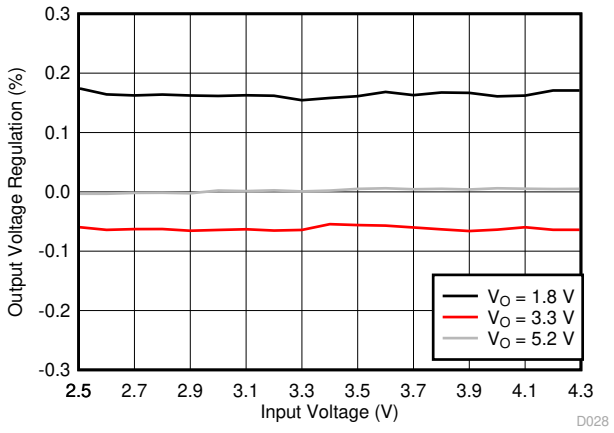
V_O = 3.3 V MODE = High

Figure 10-11. Load Regulation (PWM Only)



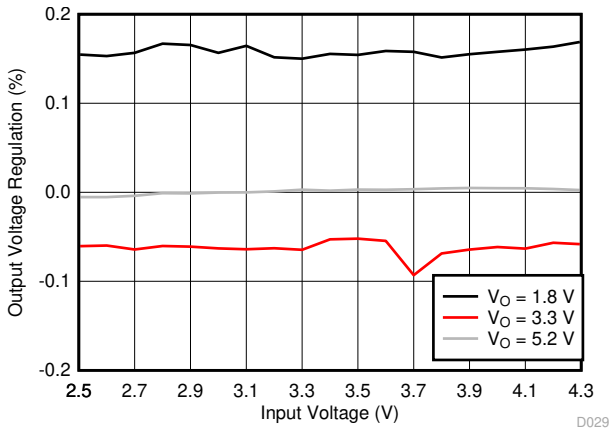
V_O = 3.3 V MODE = Low

Figure 10-12. Load Regulation (PFM/PWM)



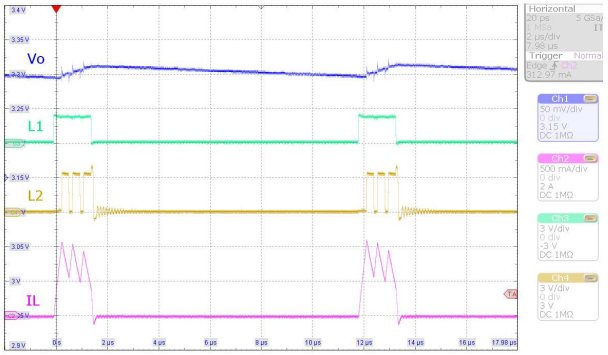
I_O = 1 A MODE = Low

Figure 10-13. Line Regulation (PWM Only)



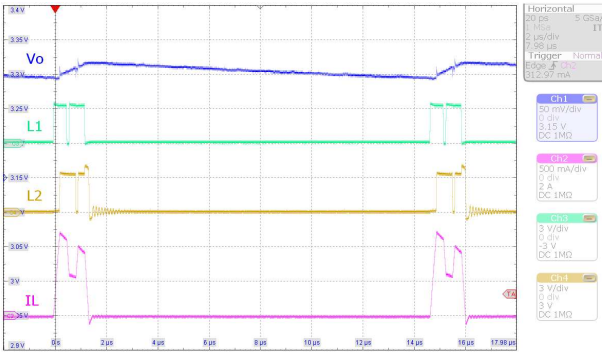
I_O = 1 A MODE = High

Figure 10-14. Line Regulation (PFM/PWM)



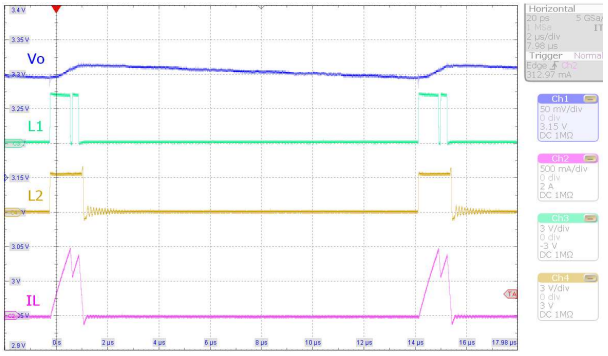
V_I = 2.3 V, V_O = 3.3 V MODE = Low I_O = 40 mA

Figure 10-15. Switching Waveforms, PFM Boost Operation



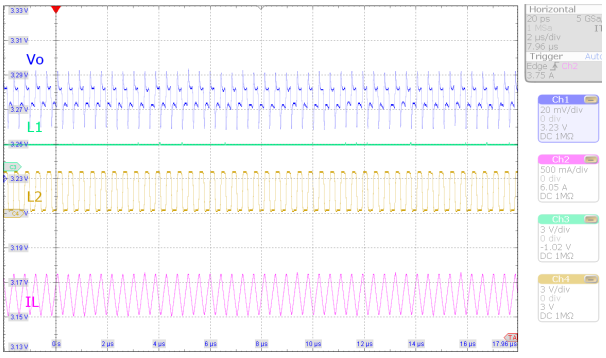
V_I = 3.3 V, V_O = 3.3 V MODE = Low I_O = 40 mA

Figure 10-16. Switching Waveforms, PFM Buck-Boost Operation



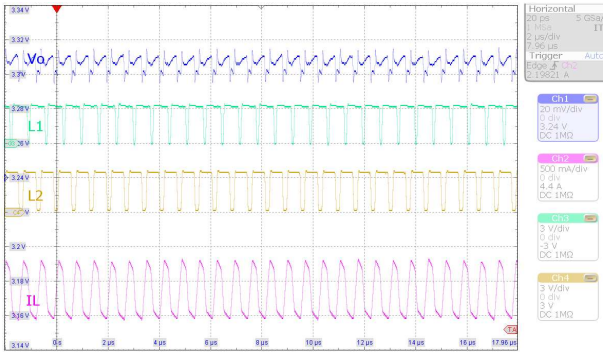
V_I = 4.2 V, V_O = 3.3 V MODE = Low I_O = 40 mA

Figure 10-17. Switching Waveforms, PFM Buck Operation



V_I = 2.3 V, V_O = 3.3 V MODE = Low I_O = 2 A

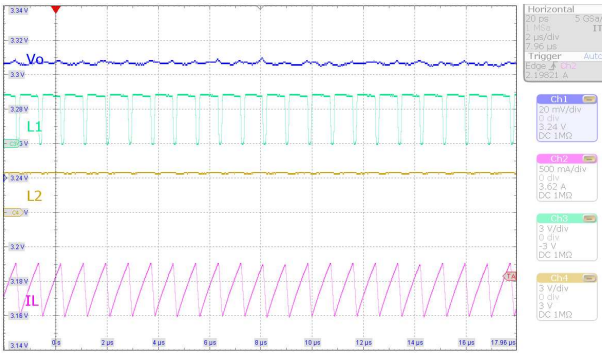
Figure 10-18. Switching Waveforms, PWM Boost Operation



V_I = 3.3 V, V_O = 3.3 V MODE = Low I_O = 2 A

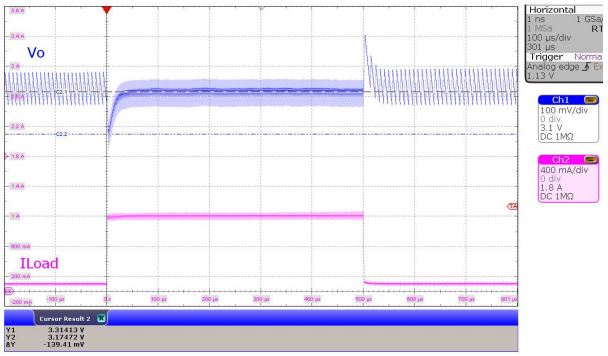
Figure 10-19. Switching Waveforms, PWM Buck-Boost Operation

Copyright © 2021 Texas Instruments Incorporated



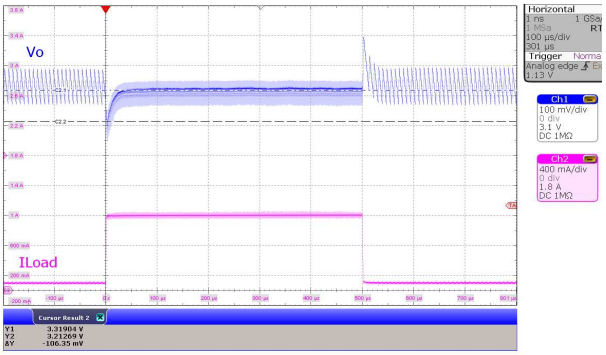
V_I = 4.2 V, V_O = 3.3 V MODE = Low I_O = 2 A

Figure 10-20. Switching Waveforms, PWM Buck Operation



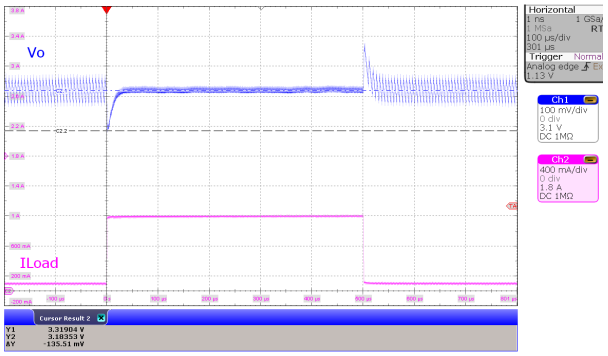
V_I = 2.5 V, V_O = 3.3 V I_O from 100 mA to 1 A t_r = 1 µs, t_f = 1 µs MODE = Low

Figure 10-21. Load Transient, PFM/PWM Boost Operation



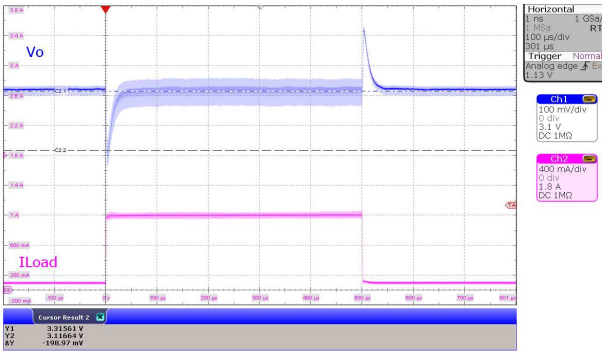
V_I = 3.3 V, V_O = 3.3 V I_O from 100 mA to 1 A t_r = 1 µs, t_f = 1 µs MODE = Low

Figure 10-22. Load Transient, PFM/PWM Buck-Boost Operation



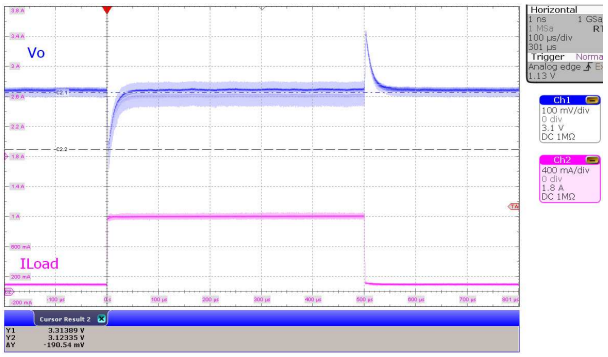
V_I = 5 V, V_O = 3.3 V I_O from 100 mA to 1 A t_r = 1 µs, t_f = 1 µs MODE = Low

Figure 10-23. Load Transient, PFM/PWM Buck Operation



V_I = 2.5 V, V_O = 3.3 V I_O from 100 mA to 1 A t_r = 1 µs, t_f = 1 µs MODE = High

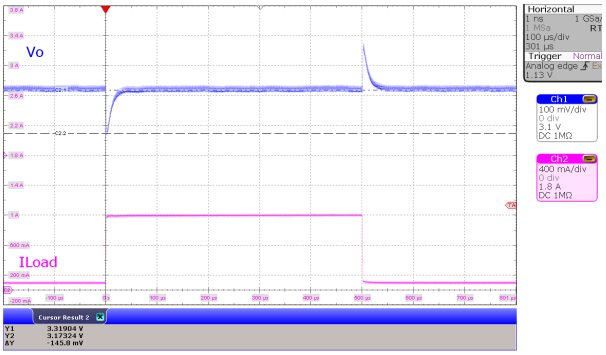
Figure 10-24. Load Transient, PWM Boost Operation



V_I = 3.3 V, V_O = 3.3 V I_O from 100 mA to 1 A t_r = 1 µs, t_f = 1 µs MODE = High

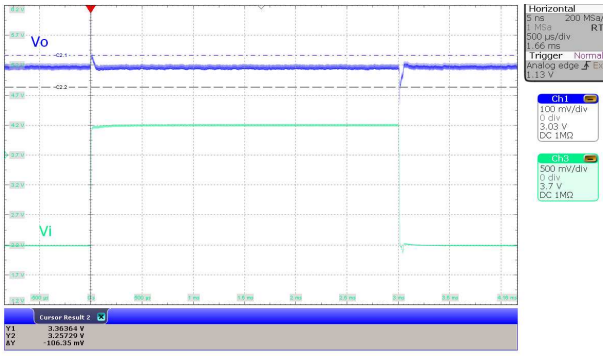
Figure 10-25. Load Transient, PWM Buck-Boost Operation

Copyright © 2021 Texas Instruments Incorporated



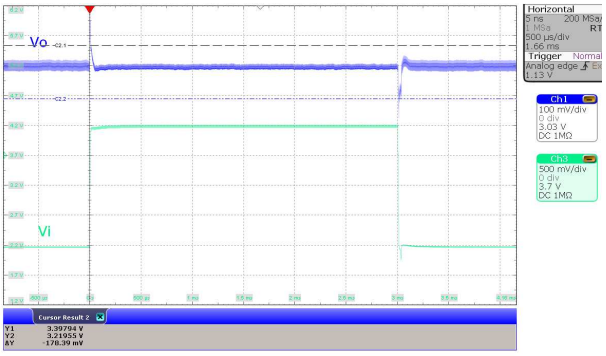
V_I = 5 V, V_O = 3.3 V | I_O from 100 mA to 1 A t_r = 1 µs, t_f = 1 µs | MODE = High

Figure 10-26. Load Transient, PWM Buck Operation



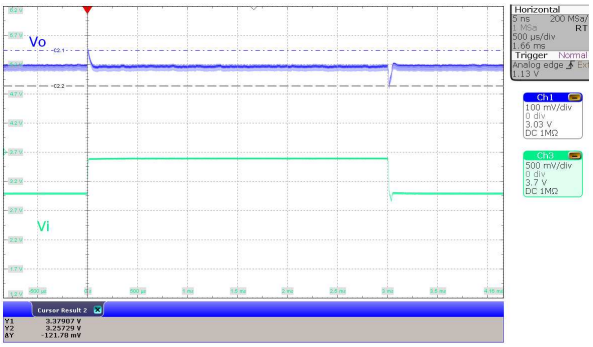
I_O = 0.5 A | V_I from 2.2 V to 4.2 V t_r =1 µs, t_f = 1 µs | MODE = High

Figure 10-27. Line Transient, PWM Operation



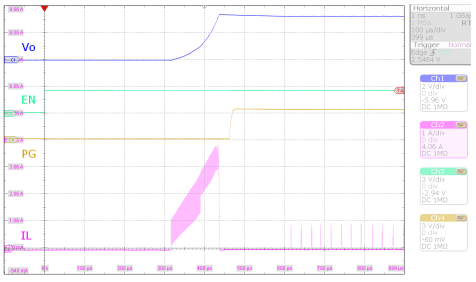
I_O = 1 A | V_I from 2.2 V to 4.2 V t_r = 1 µs, t_f = 1 µs | MODE = High

Figure 10-28. Line Transient, PWM Operation



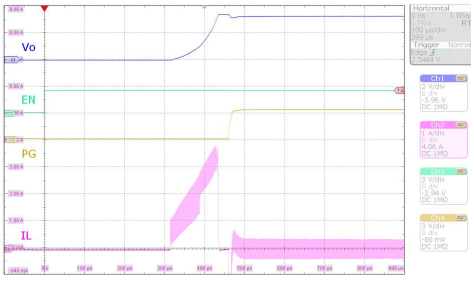
I_O = 0.5 A | V_I from 3 V to 3.6 V t_r = 1 µs, t_f = 1 µs | MODE = High

Figure 10-29. Line Transient, PWM Operation



V_I = 4.2 V, V_O = 3.3 V | MODE = Low | 100 mΩ resistive load

Figure 10-30. Start-up Behavior from Rising Enable, PFM Operation



V_I = 4.2 V, V_O = 3.3 V | MODE = High | 100 mΩ resistive load

Figure 10-31. Start-up Behavior from Rising Enable, PWM Operation

Copyright © 2021 Texas Instruments Incorporated

11 Power Supply Recommendations

The TPS63802 device family has no special requirements for its input power supply. The input power supply output current needs to be rated according to the supply voltage, output voltage, and output current of the TPS63802.

Copyright © 2021 Texas Instruments Incorporated

12 Layout

12.1 Layout Guidelines

The PCB layout is an important step to maintain the high performance of the TPS63802 device.

1. Place input and output capacitors as close as possible to the IC. Traces need to be kept short. Route wide and direct traces to the input and output capacitor results in low trace resistance and low parasitic inductance.
2. Use a common ground node for power ground and a different one for control ground to minimize the effects of ground noise. Connect these ground nodes at any place close to one of the ground pins of the IC.
3. Use separate traces for the supply voltage of the power stage and the supply voltage of the analog stage.
4. The sense trace connected to FB is signal trace. Keep these traces away from L1 and L2 nodes.

12.2 Layout Example

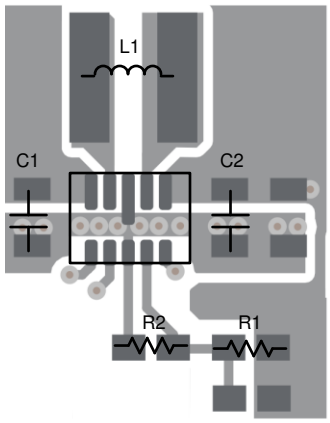


Figure 12-1. TPS63802 Layout

Copyright © 2021 Texas Instruments Incorporated

13 Device and Documentation Support

13.1 Device Support

13.1.1 Third-Party Products Disclaimer

TI'S PUBLICATION OF INFORMATION REGARDING THIRD-PARTY PRODUCTS OR SERVICES DOES NOT CONSTITUTE AN ENDORSEMENT REGARDING THE SUITABILITY OF SUCH PRODUCTS OR SERVICES OR A WARRANTY, REPRESENTATION OR ENDORSEMENT OF SUCH PRODUCTS OR SERVICES, EITHER ALONE OR IN COMBINATION WITH ANY TI PRODUCT OR SERVICE.

13.1.2 Development Support

QFN/SON Package FAQs

13.1.2.1 Custom Design With WEBENCH® Tools

Click here to create a custom design using the TPS63802 device with the WEBENCH® Power Designer.

1. Start by entering the input voltage (V_{IN}), output voltage (V_{OUT}), and output current (I_{OUT}) requirements.
2. Optimize the design for key parameters such as efficiency, footprint, and cost using the optimizer dial.
3. Compare the generated design with other possible solutions from Texas Instruments.

The WEBENCH Power Designer provides a customized schematic along with a list of materials with real-time pricing and component availability.

In most cases, these actions are available:

- Run electrical simulations to see important waveforms and circuit performance
- Run thermal simulations to understand board thermal performance
- Export customized schematic and layout into popular CAD formats
- Print PDF reports for the design, and share the design with colleagues

Get more information about WEBENCH tools at www.ti.com/WEBENCH.

13.2 Documentation Support

13.2.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, *Selecting a DC/DC Converter for Maximum Battery Life in Pulsed-Load Applications Application Report*
- Texas Instruments, *Selecting the Right DC/DC Converter for Maximum Battery Life Application Report*
- Texas Instruments, *Supercapacitor Backup Power Supply with TPS63802 Application Report*
- Texas Instruments, *Extend Battery Lifetime in Wireless Network Cameras and Video Doorbells Application Note*
- Texas Instruments, *Prevent Battery Overdischarge with Precise Threshold Enable Pin Application Note*
- Texas Instruments, *Using Non-Inverting Buck-Boost Converter for Voltage Stabilization Application Report*
- Texas Instruments, *Precise Delayed Start-up with Precise Threshold Enable-pin Application Note*
- Texas Instruments, *Buck-Boost Converters Solving Power Challenges in Optical Modules Application Note*
- Texas Instruments, *Improving Load Transient Response for Controlled Loads Application Report*
- Texas Instruments, *TPS63802EVM User's Guide*
- Texas Instruments, *HotRod QFN Package PCB Attachment Application Report*

13.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

Copyright © 2021 Texas Instruments Incorporated

13.4 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

13.5 Trademarks

TI E2E™ is a trademark of Texas Instruments.
WEBENCH® is a registered trademark of Texas Instruments.
All trademarks are the property of their respective owners.

13.6 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

13.7 Glossary

TI Glossary This glossary lists and explains terms, acronyms, and definitions.

14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

Copyright © 2021 Texas Instruments Incorporated

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS63802DLAR	Active	Production	VSON-HR (DLA) | 10	3000 | LARGE T&R	Yes	Call TI | Sn	Level-1-260C-UNLIM	-40 to 125	63802
TPS63802DLAR.A	Active	Production	VSON-HR (DLA) | 10	3000 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	63802
TPS63802DLARG4	Active	Production	VSON-HR (DLA) | 10	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	63802
TPS63802DLARG4.A	Active	Production	VSON-HR (DLA) | 10	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	63802
TPS63802DLAT	Active	Production	VSON-HR (DLA) | 10	250 | SMALL T&R	Yes	Call TI | Sn	Level-1-260C-UNLIM	-40 to 125	63802
TPS63802DLAT.A	Active	Production	VSON-HR (DLA) | 10	250 | SMALL T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	63802

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

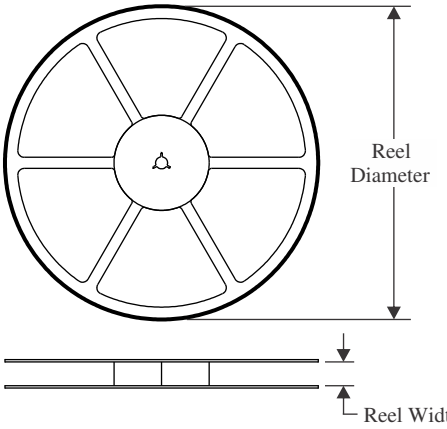
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

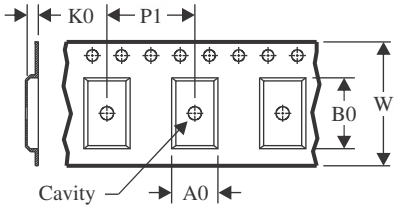
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

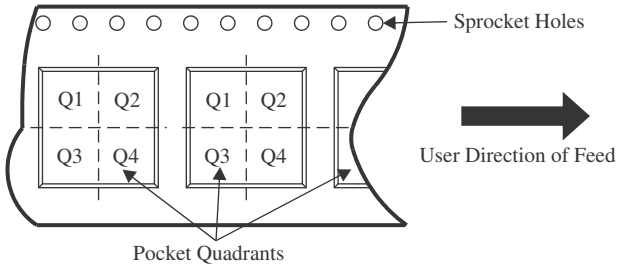


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

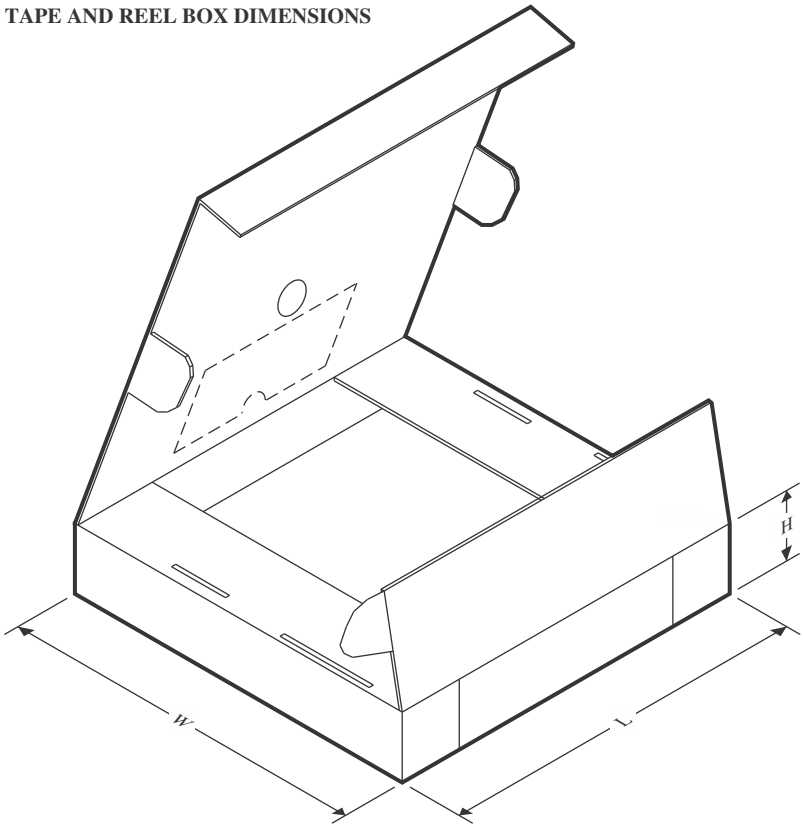
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS63802DLAT	VSON-HR	DLA	10	250	180.0	8.4	2.25	3.25	1.05	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

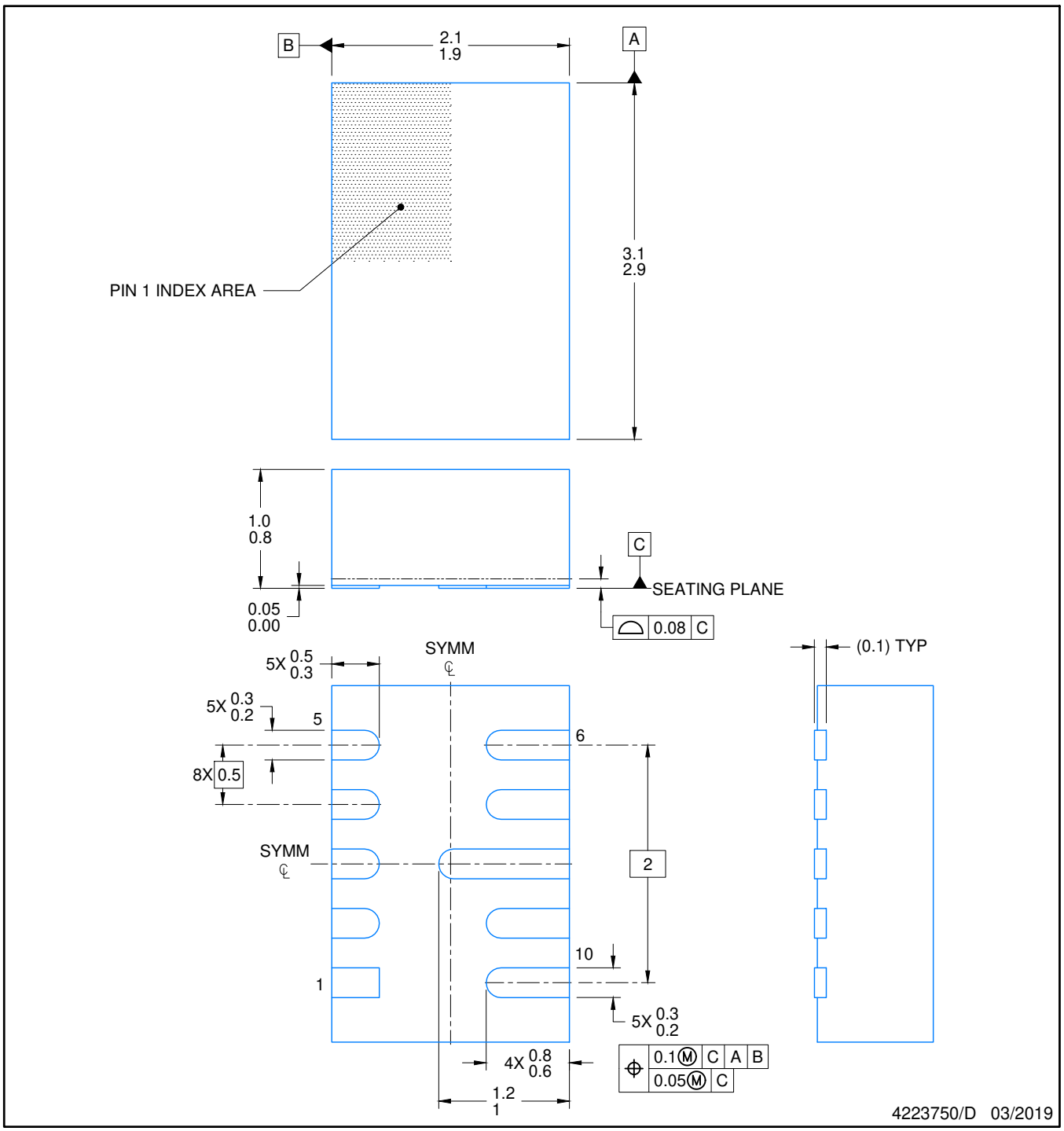
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS63802DLAT	VSON-HR	DLA	10	250	341.0	182.0	80.0

PACKAGE OUTLINE

DLA0010A

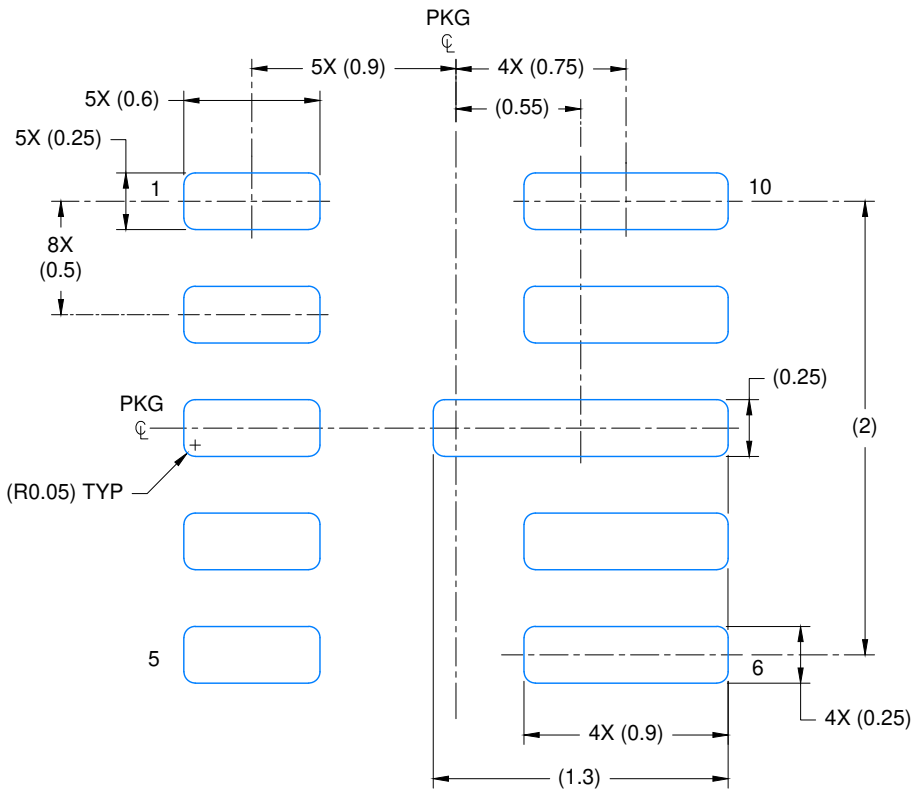
VSON-HR - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

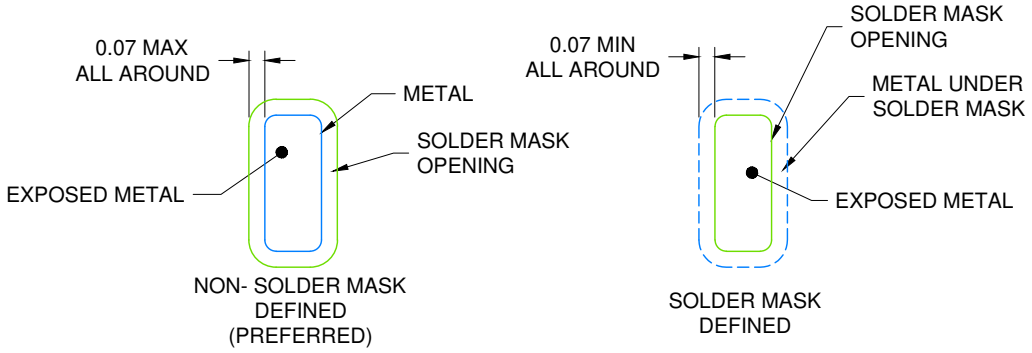


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 30X

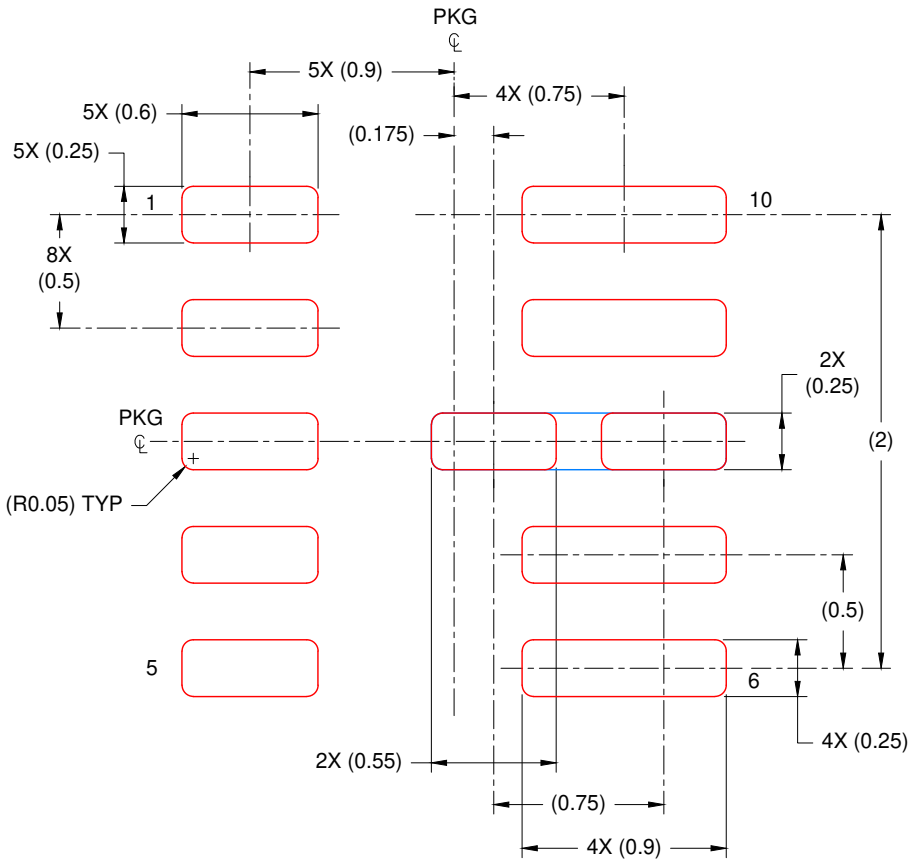


SOLDER MASK DETAILS

4223750/D 03/2019

NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
4. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
PAD 8: 83%
SCALE: 30X

4223750/D 03/2019

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale, TI’s General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025